

Thin Film Power Resistors



Product may not be to scale

The PWB series resistor chips offer a 1 W power rating in a relatively small size. They offer one of the best combinations of size and power available.

The PWBs are manufactured using Vishay Electro-Films (EFI) sophisticated thin film equipment and manufacturing technology. The PWBs are 100 % electrically tested and visually inspected to MIL-STD-883.

FEATURES

Wire bondable

Power: 1 W

• Chip size: 0.070 inches square

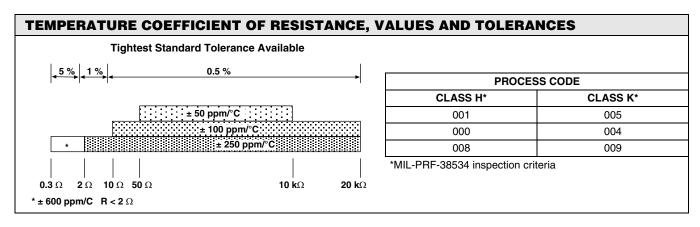
• Resistance range: 0.3 Ω to 20 k Ω

• Oxidized silicon substrate for good power dissipation

· Resistor material: Tantalum nitride, self-passivating

APPLICATIONS

The PWB resistor chips are used mainly in higher power circuits of amplifiers where increased power loads require a more specialized resistor.



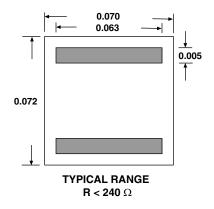
| STANDARD ELECTRICAL SPECIFICATIONS | | |
|---|------------------------------------|--|
| PARAMETER | | |
| Noise, MIL-STD-202, Method 308 100 Ω - 250 k Ω < 100 Ω or > 251 k Ω | - 35 dB typ. - 20 dB typ. | |
| MoistureResistance, MIL-STD-202 Method 106 | ± 0.5 % max. Δ <i>R</i> / <i>R</i> | |
| Stability, 1000 h, + 125 °C, 500 mW | \pm 0.5 % max. $\Delta R/R$ | |
| Operating Temperature Range | - 55 °C to + 125 °C | |
| Thermal Shock, MIL-STD-202, Method 107, Test Condition F | ± 0.1 % max. Δ <i>R</i> / <i>R</i> | |
| High Temperature Exposure, + 150 °C, 100 h | ± 0.2 % max. Δ <i>R</i> / <i>R</i> | |
| Dielectric Voltage Breakdown | 200 V | |
| Insulation Resistance | 10 ¹² min. | |
| Operating Voltage Steady State 5 x Rated Power | 100 V max. 200 V max. | |
| DC Power Rating at + 70 °C (Derated to Zero at + 175 °C) (Conductive Epoxy Die Sttach to Alumina Substrate) | 1 W | |
| 5 x Rated Power Short-Time Overload, + 25 °C, 5 s | ± 0.25 % max. Δ <i>R/R</i> % | |

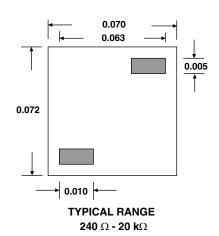
For technical questions, contact: <u>efi@vishay.com</u>

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Revision: 12-Mar-08

DIMENSIONS in inches





SCHEMATIC



| MECHANICAL SPECIFICATIONS in inches | | | | |
|-------------------------------------|--|--|--|--|
| PARAMETER | | | | |
| Chip Size | 0.070 x 0.070 ± 0.005 (1.781 x 1.781 mm) | | | |
| Chip Thickness | 0.010 ± 0.002 (0.254 ± 0.05 mm) | | | |
| Chip Substrate Material | Oxidized silicon, 10 kÅ minimum SiO ₂ | | | |
| Resistor Material | Tantalum nitride, self-passivating | | | |
| Bonding Pad Size | 0.005 x 0.010 (0.127 x 0.254 mm) minimum | | | |
| Number of Pads | 2 | | | |
| Pad Material | 10 kÅ minimum aluminum | | | |
| Backing | None, lapped semiconductor silicon | | | |

Gold back for eutectic die attach Options:

Gold bonding pads, 15 kÅ minimum thickness

Consult Applications Engineer

| ORDERING INFORMATION | | | | | | | |
|---|--------------------------|---|--|--|---|--|--|
| Example: 100 % visual, 10 kΩ, ± 1 %, ± 100 ppm/°C TCR, aluminum pads, class H visual inspection | | | | | | | |
| W INSPECTION/ PACKAGING W = 100 % visually inspected parts in matrix trays per | PWB PRODUCT FAMILY | 000 PROCESS CODE See Process Code table | 1000 RESISTANCE VALUE Use first 4 digits significant digits of the | 1 MULTIPLIER CODE D = 0.0001 C = 0.001 | F TOLERANCE CODE D = 0.5 % F = 1.0 % | | |
| MIL-STD-883 X = Sample, visually inspected parts loaded in matrix trays (4 % AQL) | | | resistance | B = 0.01 A = 0.1 0 = 1 1 = 10 | G = 2.0 % H = 2.5 % J = 5.0 % K = 10 % | | |

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